

# H233-Z80-AAN1

High Density Server - 2U 2-Node DP 4 x PCIe GPUs



## Features

- Supports up to 4 x Dual slot Gen5 GPUs
- 2U 2-node rear access server system
- Dual AMD EPYC™ 9005/9004 Series Processors per node
- 12-Channel DDR5 RDIMM, 24 x DIMMs per node
- Dual ROM Architecture
- 4 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 2.5" Gen4 NVMe hot-swap bays
- 4 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x LP PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 2600W 80 PLUS Titanium redundant power supply

## Application

AI, AI Training, AI Inference, HPC, HCI, Hybrid/Private Cloud Server

## Specification

<b>Dimensions</b>	2U 2-Node - Rear access (W440 x H87.5 x D877 mm)	<b>Backplane Board</b>	Speed and bandwidth: PCIe Gen4 x4
<b>Motherboard</b>	MZ83-HD0	<b>TPM</b>	1 x TPM headers with SPI interface (per node) - Optional TPM2.0 kit: CTM010
<b>CPU</b>	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processor per node cTDP up to 240W	<b>Power Supply</b>	Dual 2600W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
<b>Socket</b>	2 x LGA 6096 (Socket SP5)	<b>System Management</b>	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
<b>Chipset</b>	System on Chip	<b>OS Support</b>	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
<b>Memory</b>	12-Channel DDR5 RDIMM, 48 x DIMMs [EPYC 9005] RDIMM: Up to 6000 MT/s [EPYC 9004] RDIMM: Up to 4800 MT/s	<b>System Fans</b>	4 x 80x80x80mm (16,500rpm)
<b>LAN</b>	4 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - Support NCSI function 2 x 10/100/1000 management LAN	<b>Operating Properties</b>	Operating temperature: 10°C to 30°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>Video</b>	Integrated in ASPEED® AST2600 x 2 - 2 x Mini-DP	<b>Packaging Content</b>	1 x H233-Z80-AAN1, 4 x CPU heatsinks, 1 x 3-Section Rail Kit, 1 x Mini-DP to D-Sub cable, 4 x GPU power cables (CPU 8pin) Packaging Dimensions: 1179 x 700 x 380 mm
<b>Storage</b>	Front hot-swap: 4 x 2.5" Gen4 NVMe	<b>Part Numbers</b>	Barebone package: 6NH233Z80DR000ACN1* Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R - RMA packaging: 6NH233Z80SR-RMA-A100
<b>SAS</b>	N/A		
<b>RAID</b>	N/A		
<b>Expansion Slots</b>	4 x FHFL PCIe Gen5 x16 slots for GPUs 2 x LP PCIe Gen5 x16 slots 2 x OCP NIC 3.0 PCIe Gen5 x16 slots		
<b>Rear I/O</b>	4 x USB 3.2 Gen1, 2 x Mini-DP, 4 x RJ45, 2 x MLAN		



Learn more at <https://www.GIGABYTE.com/enterprise>

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